



Material Content Data Sheet



Sales Product Name	TLS810D1EJ V50			Issued	13. August 2019			
MA#	MA003286546							
Package	PG-DSO-8-52			Weight*	83.69 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.996	1.19	1.19	11901	11901
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8695	
wire	non noble metal	copper	7440-50-8	29.548	35.31	36.23	353055	362294
	non noble metal	copper	7440-50-8	0.062	0.07	0.07	737	737
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1207
encapsulation	plastics	epoxy resin	-	4.646	5.55		55518	
	inorganic material	silicondioxide	60676-86-0	45.756	54.67	60.34	546728	603453
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8306	8306
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8657	8657
glue	plastics	epoxy resin	-	0.097	0.12		1163	
	noble metal	silver	7440-22-4	0.292	0.35	0.47	3489	4652
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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